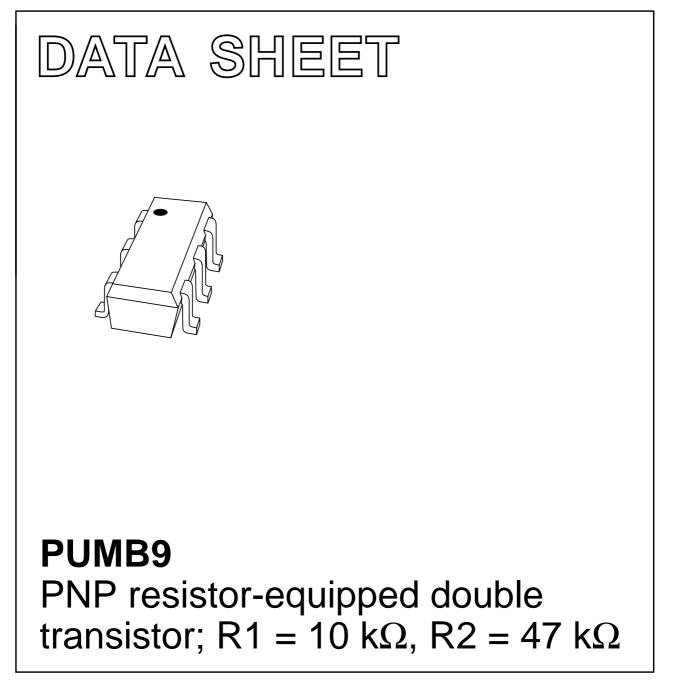
DISCRETE SEMICONDUCTORS



Objective specification

2003 Feb 03



PUMB9

FEATURES

- Built-in bias resistors: R1 (typ. 10 kΩ); R2 (typ. 47 kΩ)
- Simplification of circuit design
- Reduces number of components and board space.

APPLICATIONS

- Interface circuits
- Load driver in digital circuits.

DESCRIPTION

PNP resistor-equipped double transistor in an SC-88 (SOT363) plastic package.

MARKING

TYPE NUMBER	MARKING CODE ⁽¹⁾		
PUMB9	B*9		

Note

1. * = p: Made in Hong Kong.

* = t: Made in Malaysia.

PINNING

PIN	DESCRIPTION		
1, 4	emitter	TR1; TR2	
2, 5	base	TR1; TR2	
6, 3	collector	TR1; TR2	

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V _{CEO}	collector-emitter voltage	-50	V
I _{CM}	peak collector current	-100	mA
TR1	PNP	_	-
TR2	PNP	_	_
R1	bias resistor	10	kΩ
R2	bias resistor	47	kΩ

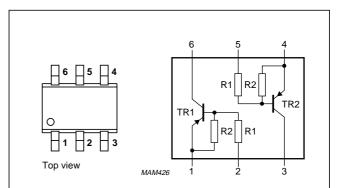


Fig.1 Simplified outline (SC-88; SOT363) and symbol.

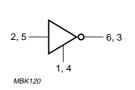


Fig.2 Equivalent inverter symbol.

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per transist	tor				-
V _{CBO}	collector-base voltage	open emitter	-	-50	V
V _{CEO}	collector-emitter voltage	open base	_	-50	V
V _{EBO}	emitter-base voltage	open collector	-	-10	V
VI	input voltage				
	positive		_	+6	V
	negative		_	-40	V
lo	output current (DC)		_	-100	mA
I _{CM}	peak collector current		_	-100	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	_	200	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C
Per device					•
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	_	300	mW

Note

1. Transistor mounted on an FR4 printed-circuit board, single-sided copper, tinplated and standard footprint.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT	
R _{th j-a}	thermal resistance from junction to ambient	note 1	416	K/W	

Note

1. Transistor mounted on an FR4 printed-circuit board, single-sided copper, tinplated and standard footprint.

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CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

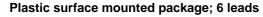
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Per transist	Per transistor					
I _{CBO}	collector-base cut-off current	$V_{CB} = -50 \text{ V}; I_E = 0$	-	-	-100	nA
I _{CEO}	collector-emitter cut-off current	$V_{CE} = -30 \text{ V}; I_B = 0$	-	-	-1	μA
		$V_{CE} = -30 \text{ V}; \text{ I}_{B} = 0; \text{ T}_{j} = 150 ^{\circ}\text{C}$	-	-	-50	μA
I _{EBO}	emitter-base cut-off current	$V_{EB} = -5 V; I_{C} = 0$	-	-	-150	μA
h _{FE}	DC current gain	$V_{CE} = -5 \text{ V}; \text{ I}_{C} = -5 \text{ mA}$	100	-	-	
V _{CEsat}	collector-emitter saturation voltage	$I_{\rm C} = -5$ mA; $I_{\rm B} = -0.25$ mA	-	-	-100	mV
V _{i(off)}	input-off voltage	$V_{CE} = -5 \text{ V}; \text{ I}_{C} = -100 \mu\text{A}$	-	-	-0.5	V
V _{i(on)}	input-on voltage	$V_{CE} = -0.3 \text{ V}; I_C = -1 \text{ mA}$	-1.4	-	-	V
R ₁	input resistor		7	10	13	kΩ
R2 R1	resistor ratio		3.7	4.7	5.7	
C _c	collector capacitance	$I_E = i_e = 0; V_{CB} = -10 V;$ f = 1 MHz	_	_	3	pF

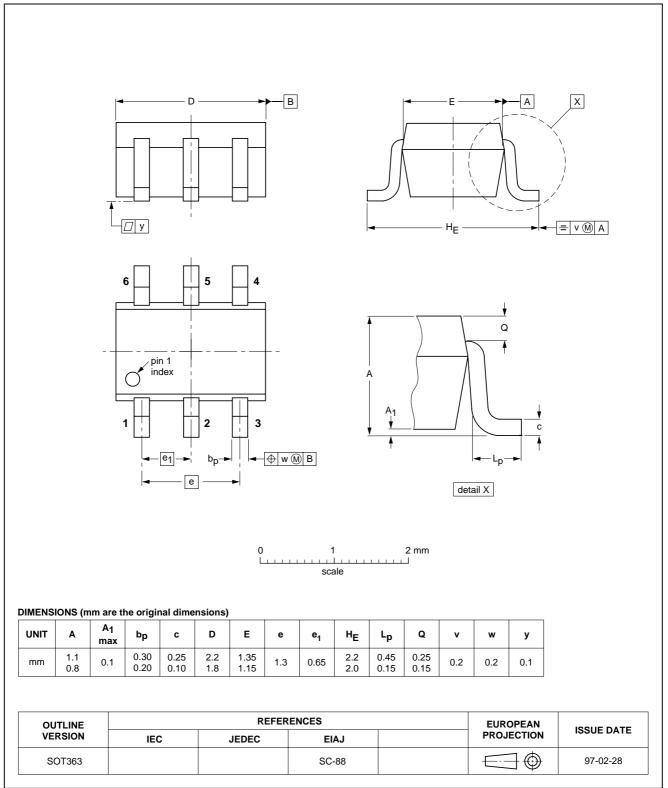
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SOT363

PNP resistor-equipped double transistor; R1 = 10 k Ω , R2 = 47 k Ω

PACKAGE OUTLINE





PUMB9

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾⁽³⁾	DEFINITION
1	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
11	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

Notes

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- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.
- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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NOTES

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